APPENDIX A

Version with markings to show changes made

IN THE SPECIFICATION

Please replace paragraph **[0001]** with the following:

[0001] Cross Reference to Related Applications: This application is a continuation of application Serial No. 09/302,083, filed April 29, 1999, [pending] now U.S. Patent 6,277,673 B1, issued August 21, 2001, which is a continuation of application Serial No. 08/774,609, filed December 30, 1996, now U.S. Patent 5,907,769, issued May 25, 1999.

IN THE CLAIMS

12. (Amended) The assembly of claim 1, wherein the die paddle includes at least one portion thereon extending beyond a longer peripheral side of the opposed peripheral sides and at least another portion thereof extending beyond [an] the end of the opposed ends of the semiconductor device.

20. (Amended) A manufacturing method for a lead frame for a semiconductor assembly having a semiconductor device having two opposed peripheral sides, two opposed ends, an active surface in a first horizontal plane, a bottom inactive surface in a second horizontal plane, and a plurality of bond pads located on the active surface of the semiconductor device, a first portion of the plurality of bond pads located adjacent one of the two opposed peripheral sides and a second portion of the plurality of bond pads located adjacent another of the two opposed peripheral sides, said method comprising:

forming a first plurality of lead fingers extending substantially in the first horizontal plane of the active surface of the semiconductor device, each lead finger of the first plurality of lead

fingers terminating in an end located adjacent a peripheral side of the two opposed peripheral sides of the semiconductor device;

forming a second plurality of lead fingers extending below the bottom inactive surface of the semiconductor device, each lead finger of the second plurality of lead fingers having a portion thereof extending adjacent an end of the two opposed ends of the semiconductor device and terminating in an end located adjacent [a] the peripheral side of the two opposed peripheral sides of the semiconductor device, at least one lead finger of the second plurality of lead fingers including a section extending substantially in the first horizontal plane; and

forming a die paddle.

28. (Amended) The method of claim 20, wherein the die paddle includes at least one portion thereon extending beyond [a] the peripheral side of the two opposed peripheral sides and at least another portion thereof extending beyond an end of the two opposed ends of the semiconductor device.

30. (Amended) The method of claim 20, wherein the second plurality of lead fingers includes:

at least one lead finger having a portion thereof extending adjacent a portion of a lead finger of the first plurality of lead fingers, a portion thereof extending substantially adjacent [an] the end of the two opposed ends of the semiconductor device, a portion extending substantially opposed to an end of the two opposed ends of the semiconductor device, and having a portion extending beyond [a] the peripheral side of the two opposed peripheral sides of the semiconductor device.

31. (Amended) The method of claim 20, wherein the second plurality of lead fingers includes:

at least one lead finger having a portion thereof extending adjacent a portion of a lead finger of the first plurality of lead fingers, a portion thereof extending substantially adjacent an end of the <u>two</u> opposed ends of the semiconductor device, a portion extending substantially opposed to an end of the opposed ends of the semiconductor device and extending adjacent a portion of the die paddle, and having a portion extending beyond [a] <u>the</u> peripheral side of the two opposed peripheral sides of the semiconductor device.